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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	133MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (4), 10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 95°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mpc866pzp133a

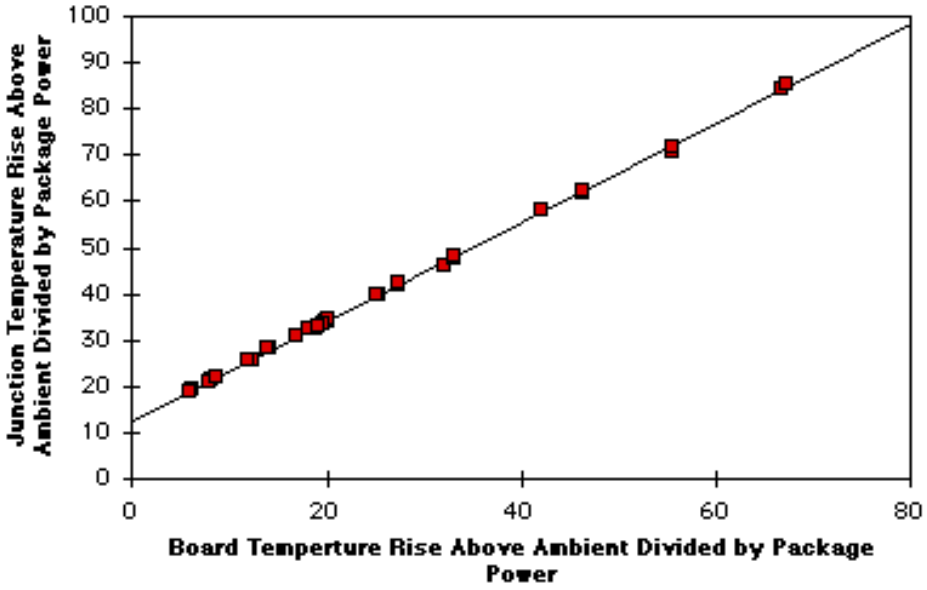


Figure 3. Effect of Board Temperature Rise on Thermal Behavior

If the board temperature is known, an estimate of the junction temperature in the environment can be made using the following equation:

$T_J = T_B + (R_{\theta JB} \times P_D)$

where:

$R_{\theta JB}$ = junction-to-board thermal resistance (ºC/W)

T_B = board temperature ºC

P_D = power dissipation in package

If the board temperature is known and the heat loss from the package case to the air can be ignored, acceptable predictions of junction temperature can be made. For this method to work, the board and board mounting must be similar to the test board used to determine the junction-to-board thermal resistance, namely a 2s2p (board with a power and a ground plane) and vias attaching the thermal balls to the ground plane.

7.4 Estimation Using Simulation

When the board temperature is not known, a thermal simulation of the application is needed. The simple two-resistor model can be used with the thermal simulation of the application [2], or a more accurate and complex model of the package can be used in the thermal simulation.

Table 9. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B12a	CLKOUT to $\overline{TA}$, $\overline{BI}$ negation (when driven by the memory controller or PCMCIA interface) (MAX = 0.00 x B1 + 9.00)	2.50	9.00	2.50	9.00	2.50	9.00	2.50	9.00	ns
B13	CLKOUT to $\overline{TS}$, $\overline{BB}$ High-Z (MIN = 0.25 x B1)	7.60	21.60	6.30	20.30	5.00	19.00	3.80	14.00	ns
B13a	CLKOUT to $\overline{TA}$, $\overline{BI}$ High-Z (when driven by the memory controller or PCMCIA interface) (MIN = 0.00 x B1 + 2.5)	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B14	CLKOUT to $\overline{TEA}$ assertion (MAX = 0.00 x B1 + 9.00)	2.50	9.00	2.50	9.00	2.50	9.00	2.50	9.00	ns
B15	CLKOUT to $\overline{TEA}$ High-Z (MIN = 0.00 x B1 + 2.50)	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B16	$\overline{TA}$, $\overline{BI}$ valid to CLKOUT (setup time) (MIN = 0.00 x B1 + 6.00)	6.00	—	6.00	—	6.00	—	6.00	—	ns
B16a	$\overline{TEA}$, $\overline{KR}$, $\overline{RETRY}$, $\overline{CR}$ valid to CLKOUT (setup time) (MIN = 0.00 x B1 + 4.5)	4.50	—	4.50	—	4.50	—	4.50	—	ns
B16b	$\overline{BB}$, $\overline{BG}$, $\overline{BR}$, valid to CLKOUT (setup time) [2] (4 MIN = 0.00 x B1 + 0.00)	4.00	—	4.00	—	4.00	—	4.00	—	ns
B17	CLKOUT to $\overline{TA}$, $\overline{TEA}$, $\overline{BI}$, $\overline{BB}$, $\overline{BG}$, $\overline{BR}$ valid (hold time) (MIN = 0.00 x B1 + 1.00 [3])	1.00	—	1.00	—	1.00	—	2.00	—	ns
B17a	CLKOUT to $\overline{KR}$, $\overline{RETRY}$, $\overline{CR}$ valid (hold time) (MIN = 0.00 x B1 + 2.00)	2.00	—	2.00	—	2.00	—	2.00	—	ns
B18	D(0:31), DP(0:3) valid to CLKOUT rising edge (setup time) [4] (MIN = 0.00 x B1 + 6.00)	6.00	—	6.00	—	6.00	—	6.00	—	ns
B19	CLKOUT rising edge to D(0:31), DP(0:3) valid (hold time) [4] (MIN = 0.00 x B1 + 1.00 [5])	1.00	—	1.00	—	1.00	—	2.00	—	ns
B20	D(0:31), DP(0:3) valid to CLKOUT falling edge (setup time) [6](MIN = 0.00 x B1 + 4.00)	4.00	—	4.00	—	4.00	—	4.00	—	ns
B21	CLKOUT falling edge to D(0:31), DP(0:3) valid (hold Time) [6] (MIN = 0.00 x B1 + 2.00)	2.00	—	2.00	—	2.00	—	2.00	—	ns
B22	CLKOUT rising edge to $\overline{CS}$ asserted GPCM ACS = 00 (MAX = 0.25 x B1 + 6.3)	7.60	13.80	6.30	12.50	5.00	11.30	3.80	10.00	ns
B22a	CLKOUT falling edge to $\overline{CS}$ asserted GPCM ACS = 10, TRLX = 0 (MAX = 0.00 x B1 + 8.00)	—	8.00	—	8.00	—	8.00	—	8.00	ns

Table 9. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B31d	CLKOUT falling edge to $\overline{CS}$ valid, as requested by control bit CST1 in the corresponding word in the UPM EBDF = 1 (MAX = 0.375 x B1 + 6.6)	13.30	18.00	11.30	16.00	9.40	14.10	7.60	12.30	ns
B32	CLKOUT falling edge to $\overline{BS}$ valid, as requested by control bit BST4 in the corresponding word in the UPM (MAX = 0.00 x B1 + 6.00)	1.50	6.00	1.50	6.00	1.50	6.00	1.50	6.00	ns
B32a	CLKOUT falling edge to $\overline{BS}$ valid, as requested by control bit BST1 in the corresponding word in the UPM, EBDF = 0 (MAX = 0.25 x B1 + 6.80)	7.60	14.30	6.30	13.00	5.00	11.80	3.80	10.50	ns
B32b	CLKOUT rising edge to $\overline{BS}$ valid, as requested by control bit BST2 in the corresponding word in the UPM (MAX = 0.00 x B1 + 8.00)	1.50	8.00	1.50	8.00	1.50	8.00	1.50	8.00	ns
B32c	CLKOUT rising edge to $\overline{BS}$ valid, as requested by control bit BST3 in the corresponding word in the UPM (MAX = 0.25 x B1 + 6.80)	7.60	14.30	6.30	13.00	5.00	11.80	3.80	10.50	ns
B32d	CLKOUT falling edge to $\overline{BS}$ valid- as requested by control bit BST1 in the corresponding word in the UPM, EBDF = 1 (MAX = 0.375 x B1 + 6.60)	13.30	18.00	11.30	16.00	9.40	14.10	7.60	12.30	ns
B33	CLKOUT falling edge to $\overline{GPL}$ valid, as requested by control bit GxT4 in the corresponding word in the UPM (MAX = 0.00 x B1 + 6.00)	1.50	6.00	1.50	6.00	1.50	6.00	1.50	6.00	ns
B33a	CLKOUT rising edge to $\overline{GPL}$ valid, as requested by control bit GxT3 in the corresponding word in the UPM (MAX = 0.25 x B1 + 6.80)	7.60	14.30	6.30	13.00	5.00	11.80	3.80	10.50	ns
B34	A(0:31), BADDR(28:30), and D(0:31) to $\overline{CS}$ valid, as requested by control bit CST4 in the corresponding word in the UPM (MIN = 0.25 x B1 - 2.00)	5.60	—	4.30	—	3.00	—	1.80	—	ns
B34a	A(0:31), BADDR(28:30), and D(0:31) to $\overline{CS}$ valid, as requested by control bit CST1 in the corresponding word in the UPM (MIN = 0.50 x B1 – 2.00)	13.20	—	10.50	—	8.00	—	5.60	—	ns
B34b	A(0:31), BADDR(28:30), and D(0:31) to $\overline{CS}$ valid, as requested by CST2 in the corresponding word in UPM (MIN = 0.75 x B1 – 2.00)	20.70	—	16.70	—	13.00	—	9.40	—	ns

Figure 10 shows normal case timing for input data. It also applies to normal read accesses under the control of the UPM in the memory controller.

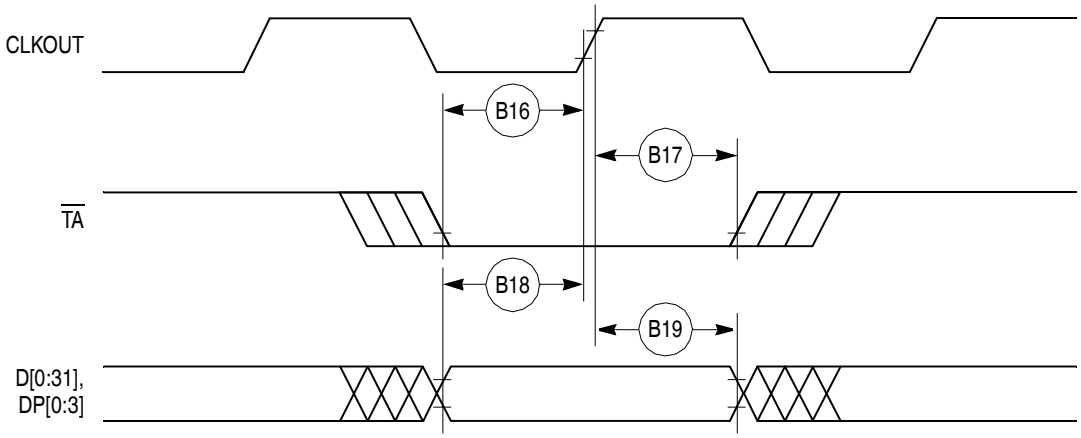


Figure 10. Input Data Timing in Normal Case

Figure 11 shows the timing for the input data controlled by the UPM for data beats where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

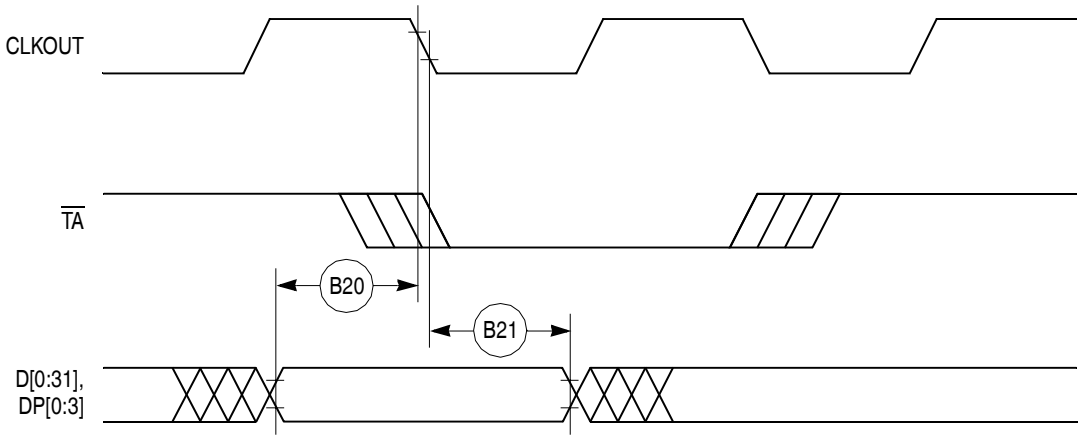


Figure 11. Input Data Timing when Controlled by UPM in the Memory Controller and DLT3 = 1

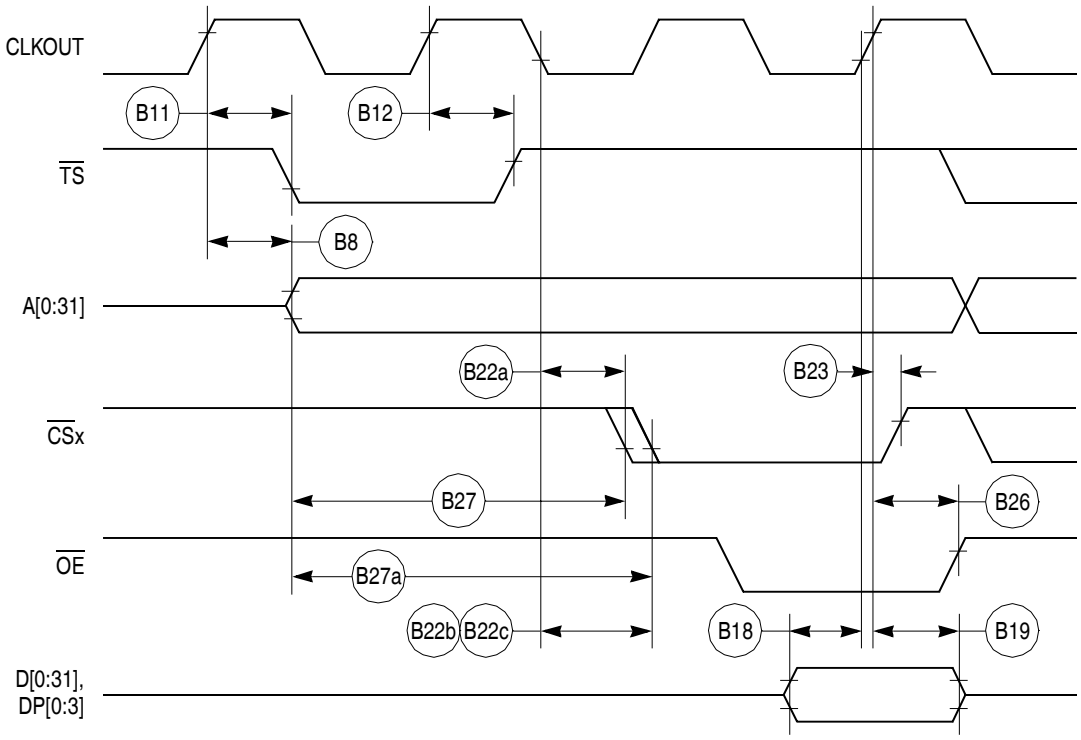


Figure 15. External Bus Read Timing (GPCM Controlled—TRLX = 0 or 1, ACS = 10, ACS = 11)

Figure 16 through Figure 18 show the timing for the external bus write controlled by various GPCM factors.

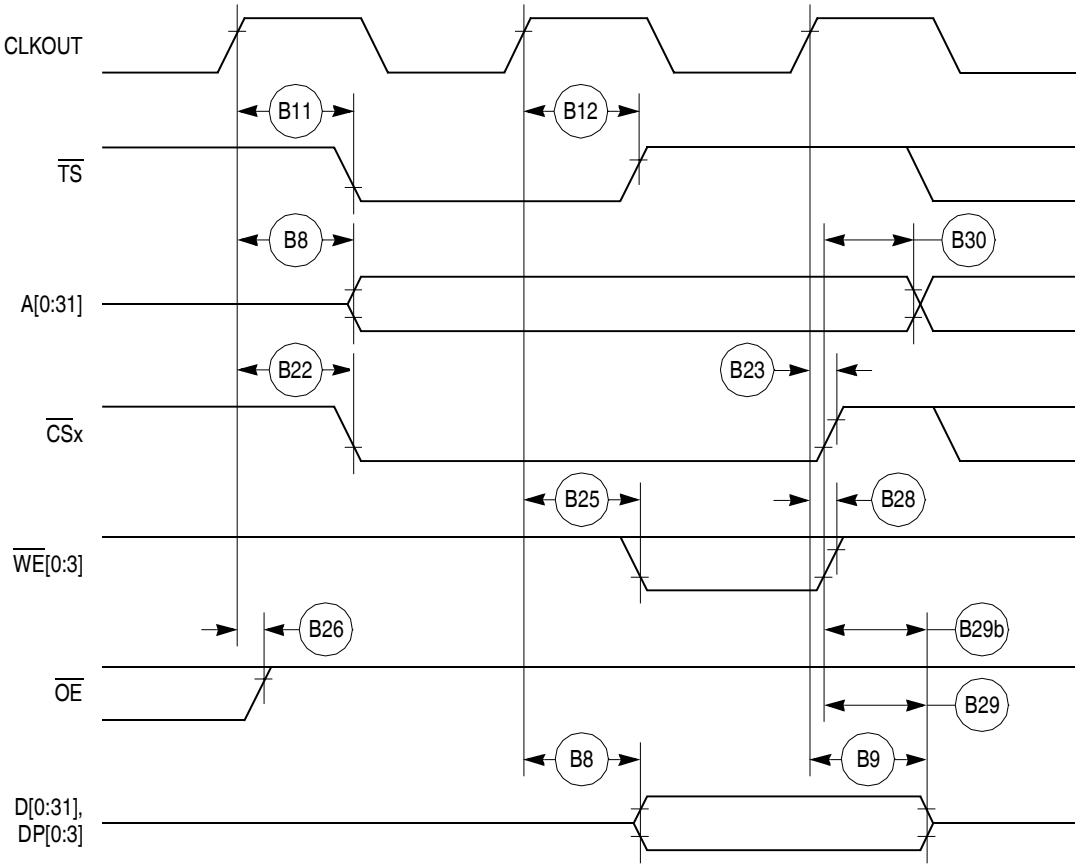


Figure 16. External Bus Write Timing (GPCM Controlled—TRLX = 0 or 1, CSNT = 0)

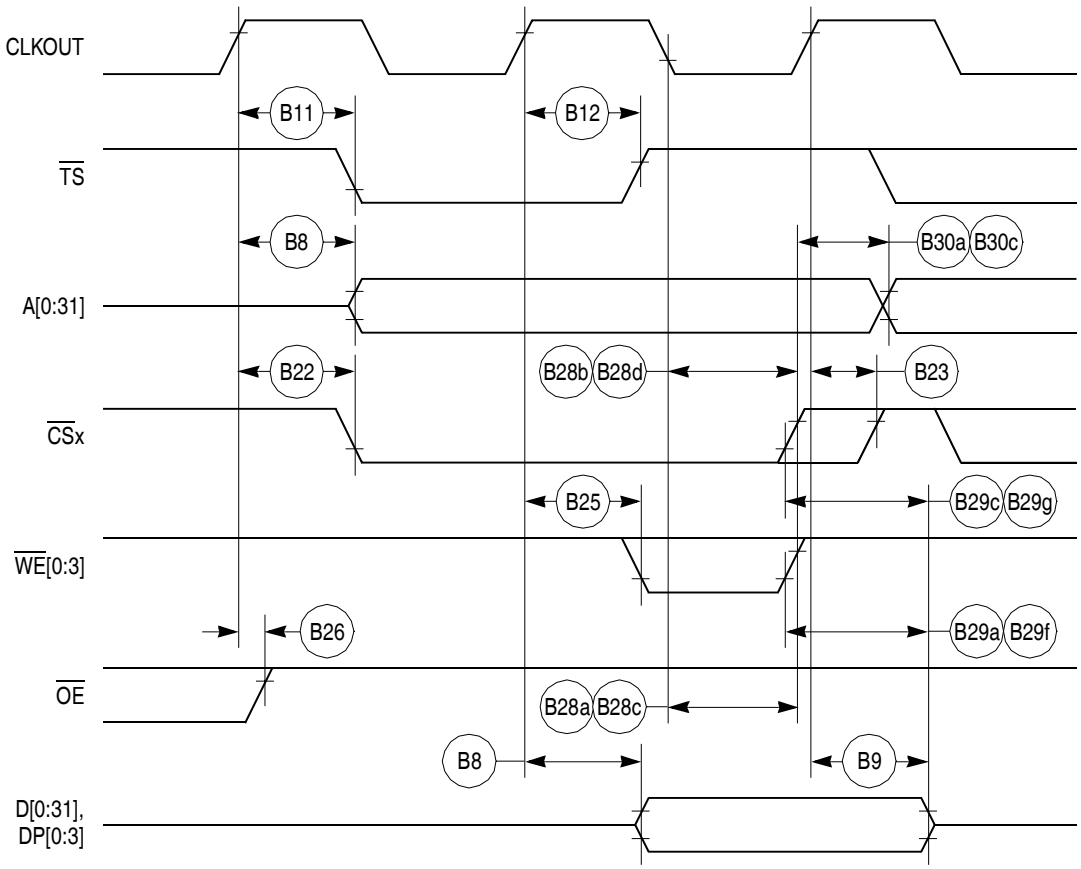


Figure 17. External Bus Write Timing (GPCM Controlled—TRLX = 0, CSNT = 1)

Figure 19 shows the timing for the external bus controlled by the UPM.

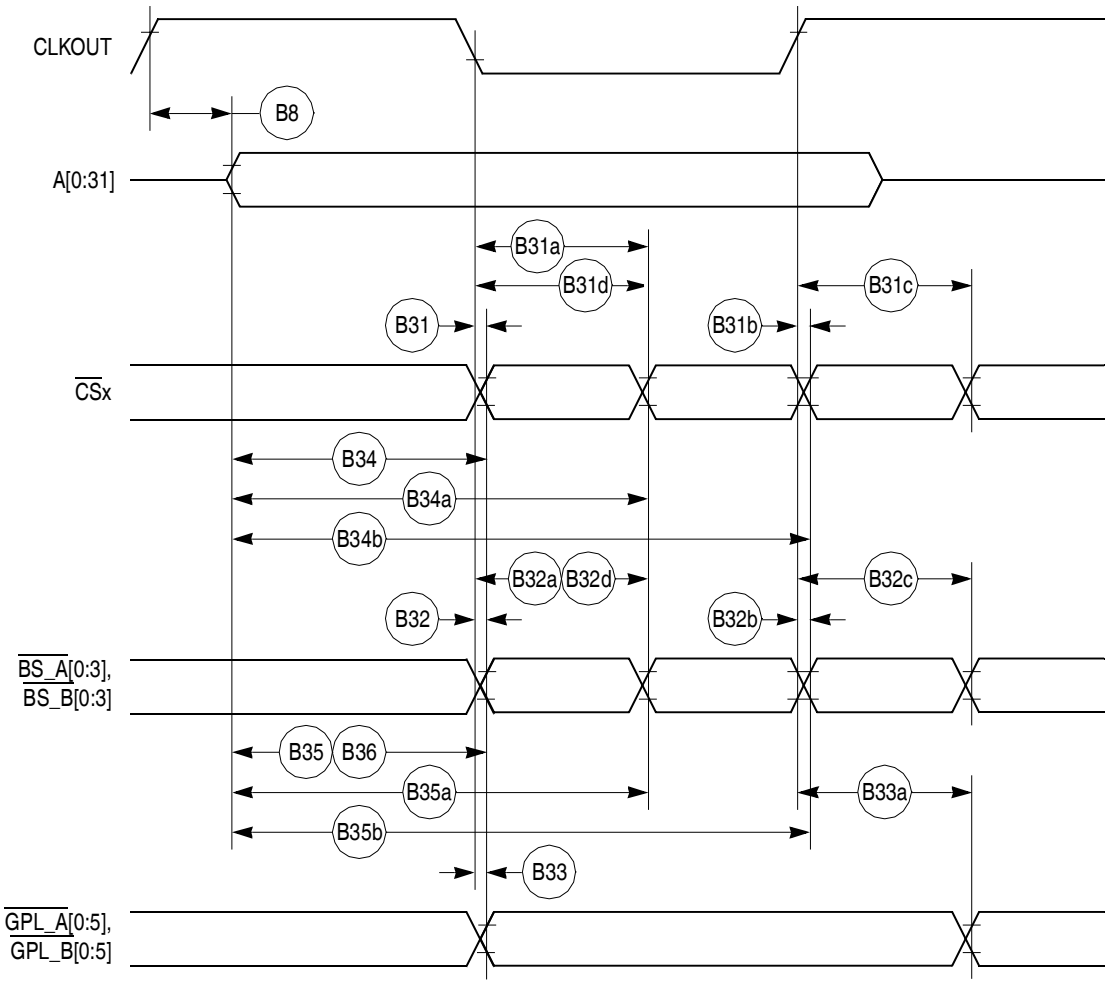


Figure 19. External Bus Timing (UPM Controlled Signals)

Figure 22 shows the timing for the synchronous external master access controlled by the GPCM.

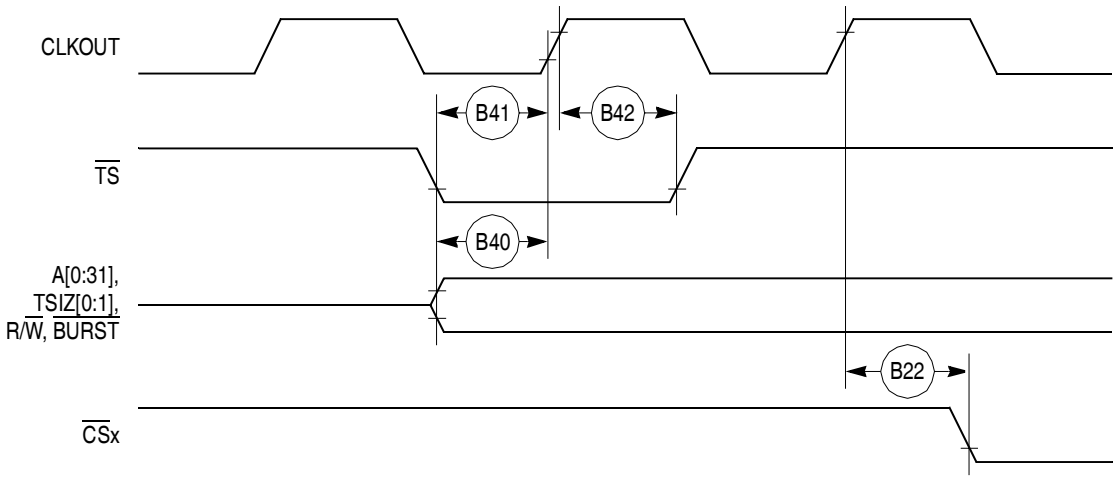


Figure 22. Synchronous External Master Access Timing (GPCM Handled ACS = 00)

Table 13 shows the debug port timing for the MPC866/859.

Table 13. Debug Port Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
D61	DSCK cycle time	$3xT_{CLOCKOUT}$	—	
D62	DSCK clock pulse width	$1.25xT_{CLOCKOUT}$	—	
D63	DSCK rise and fall times	0.00	3.00	ns
D64	DSDI input data setup time	8.00	—	ns
D65	DSDI data hold time	5.00	—	ns
D66	DSCK low to DSDO data valid	0.00	15.00	ns
D67	DSCK low to DSDO invalid	0.00	2.00	ns

Figure 32 shows the input timing for the debug port clock.

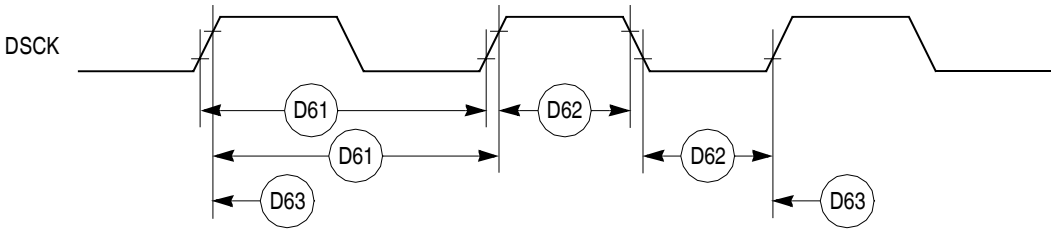


Figure 32. Debug Port Clock Input Timing

Figure 33 shows the timing for the debug port.

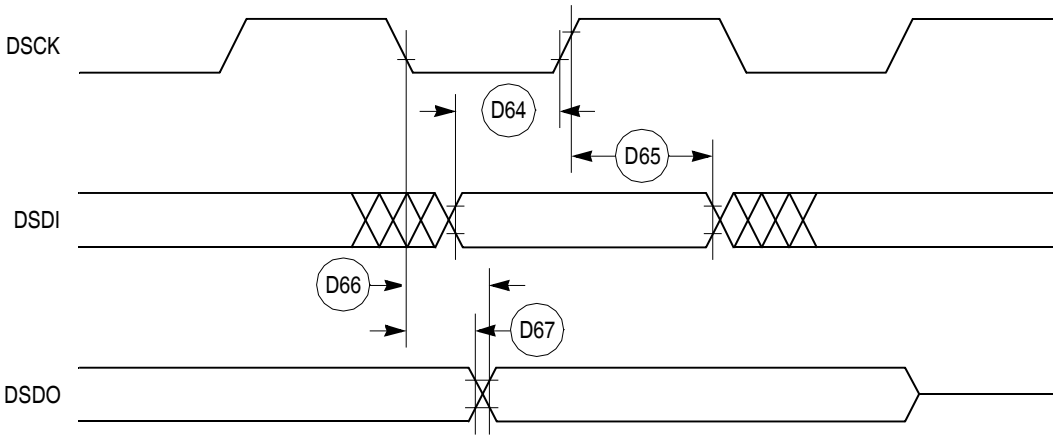


Figure 33. Debug Port Timings

Table 14 shows the reset timing for the MPC866/859.

Table 14. Reset Timing

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
R69	CLKOUT to $\overline{\text{HRESET}}$ high impedance (MAX = 0.00 x B1 + 20.00)	—	20.00	—	20.00	—	20.00	—	20.00	ns
R70	CLKOUT to $\overline{\text{SRESET}}$ high impedance (MAX = 0.00 x B1 + 20.00)	—	20.00	—	20.00	—	20.00	—	20.00	ns
R71	$\overline{\text{RSTCONF}}$ pulse width (MIN = 17.00 x B1)	515.20	—	425.00	—	340.00	—	257.60	—	ns
R72	—	—	—	—	—	—	—	—	—	—
R73	Configuration data to HRESET rising edge setup time (MIN = 15.00 x B1 + 50.00)	504.50	—	425.00	—	350.00	—	277.30	—	ns
R74	Configuration data to $\overline{\text{RSTCONF}}$ rising edge setup time (MIN = 0.00 x B1 + 350.00)	350.00	—	350.00	—	350.00	—	350.00	—	ns
R75	Configuration data hold time after $\overline{\text{RSTCONF}}$ negation (MIN = 0.00 x B1 + 0.00)	0.00	—	0.00	—	0.00	—	0.00	—	ns
R76	Configuration data hold time after $\overline{\text{HRESET}}$ negation (MIN = 0.00 x B1 + 0.00)	0.00	—	0.00	—	0.00	—	0.00	—	ns
R77	$\overline{\text{HRESET}}$ and $\overline{\text{RSTCONF}}$ asserted to data out drive (MAX = 0.00 x B1 + 25.00)	—	25.00	—	25.00	—	25.00	—	25.00	ns
R78	$\overline{\text{RSTCONF}}$ negated to data out high impedance (MAX = 0.00 x B1 + 25.00)	—	25.00	—	25.00	—	25.00	—	25.00	ns
R79	CLKOUT of last rising edge before chip three-states $\overline{\text{HRESET}}$ to data out high impedance (MAX = 0.00 x B1 + 25.00)	—	25.00	—	25.00	—	25.00	—	25.00	ns
R80	DSDI, DSCK setup (MIN = 3.00 x B1)	90.90	—	75.00	—	60.00	—	45.50	—	ns
R81	DSDI, DSCK hold time (MIN = 0.00 x B1 + 0.00)	0.00	—	0.00	—	0.00	—	0.00	—	ns
R82	$\overline{\text{SRESET}}$ negated to CLKOUT rising edge for DSDI and DSCK sample (MIN = 8.00 x B1)	242.40	—	200.00	—	160.00	—	121.20	—	ns

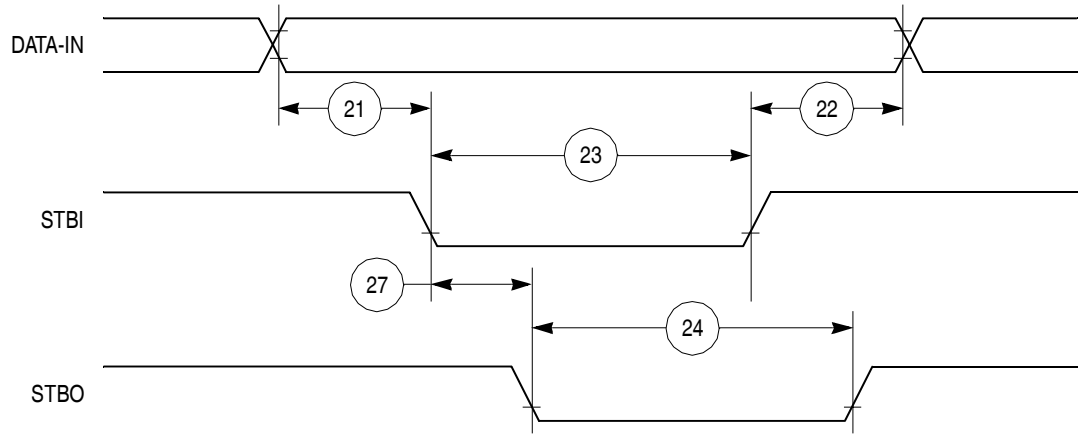


Figure 41. PIP Rx (Interlock Mode) Timing Diagram

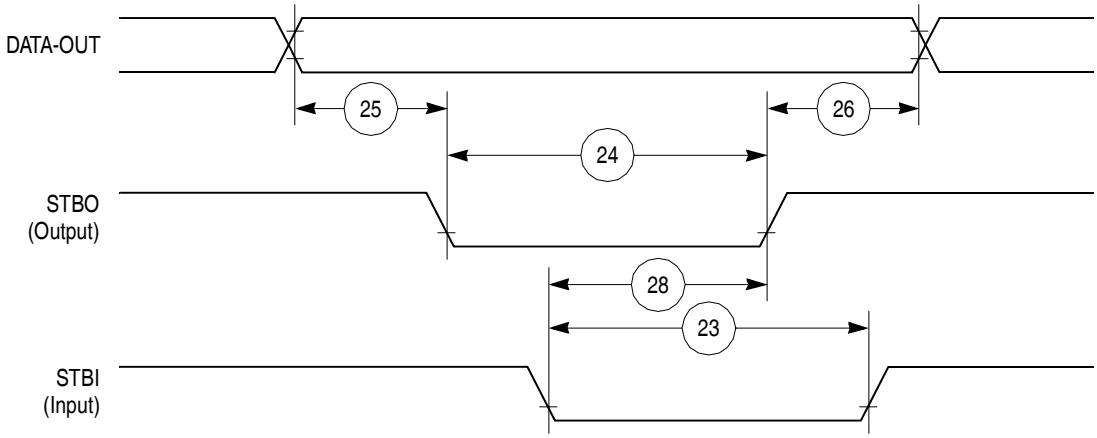


Figure 42. PIP Tx (Interlock Mode) Timing Diagram

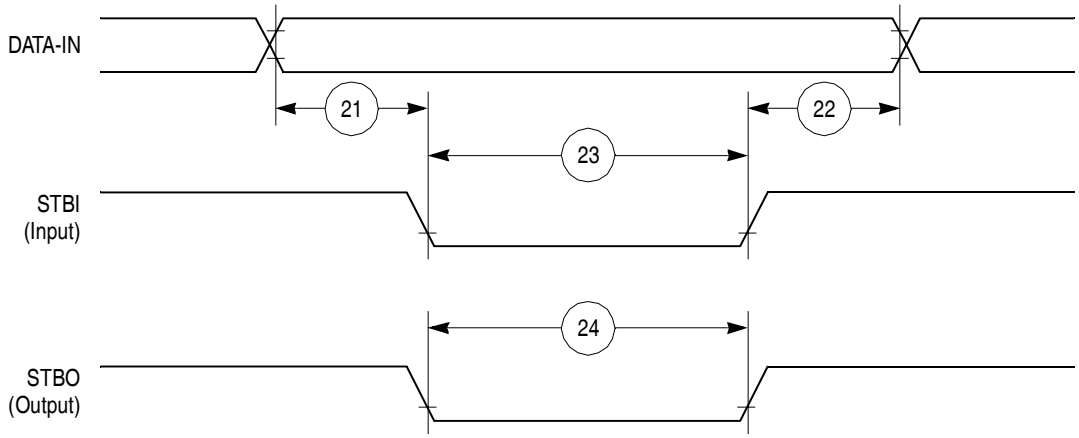


Figure 43. PIP Rx (Pulse Mode) Timing Diagram

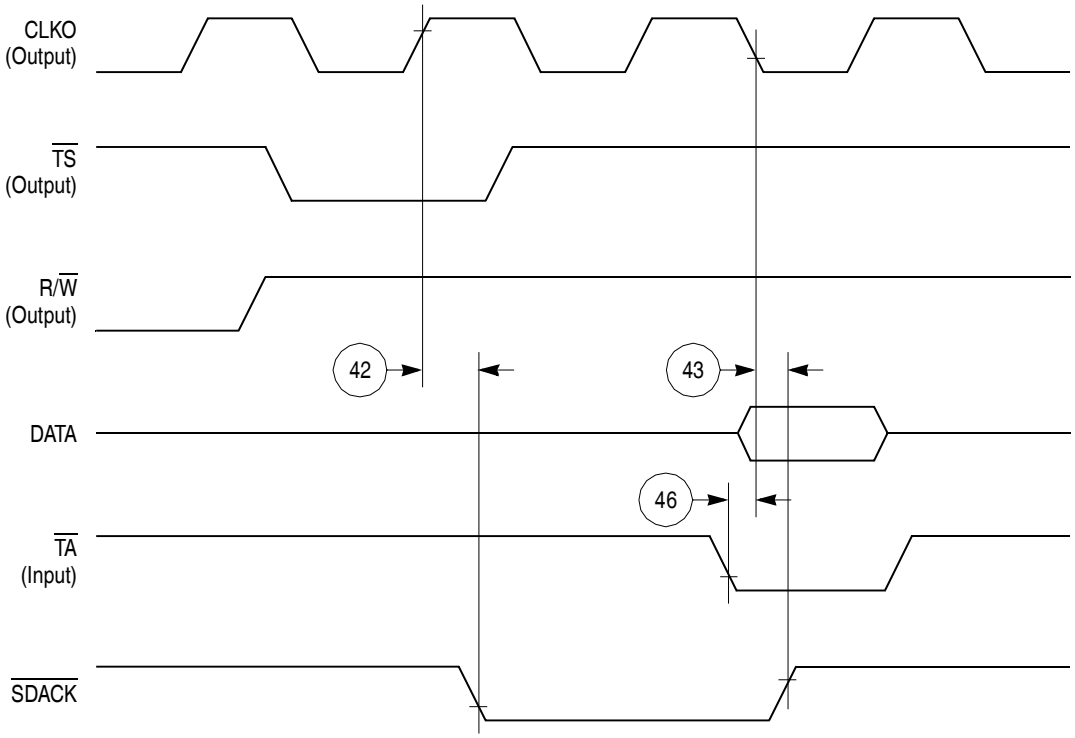


Figure 48. SDACK Timing Diagram—Peripheral Write, Externally-Generated TA

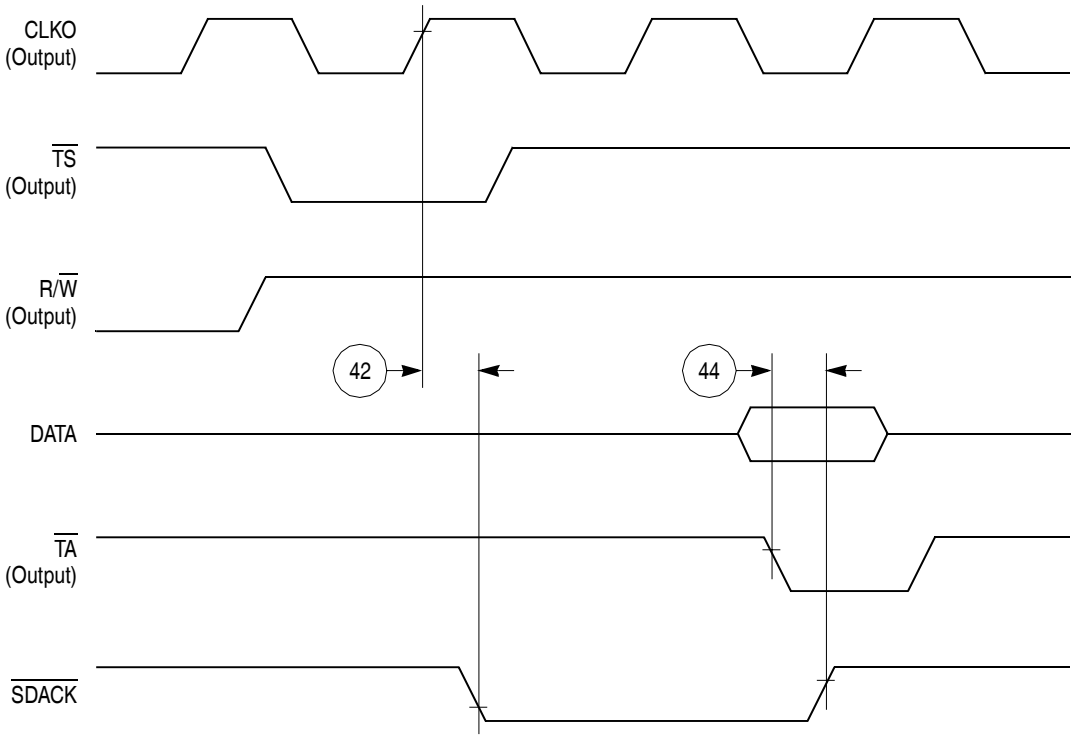


Figure 49. SDACK Timing Diagram—Peripheral Write, Internally-Generated TA

Table 21. SI Timing (continued)

Num	Characteristic	All Frequencies		Unit
		Min	Max	
74	L1CLK edge to L1RSYNC, L1TSYNC, invalid (SYNC hold time)	35.00	—	ns
75	L1RSYNC, L1TSYNC rise/fall time	—	15.00	ns
76	L1RXD valid to L1CLK edge (L1RXD setup time)	17.00	—	ns
77	L1CLK edge to L1RXD invalid (L1RXD hold time)	13.00	—	ns
78	L1CLK edge to L1ST(1–4) valid [4]	10.00	45.00	ns
78A	L1SYNC valid to L1ST(1–4) valid	10.00	45.00	ns
79	L1CLK edge to L1ST(1–4) invalid	10.00	45.00	ns
80	L1CLK edge to L1TXD valid	10.00	55.00	ns
80A	L1TSYNC valid to L1TXD valid [4]	10.00	55.00	ns
81	L1CLK edge to L1TXD high impedance	0.00	42.00	ns
82	L1RCLK, L1TCLK frequency (DSC =1)	—	16.00 or SYNCCLK/2	MHz
83	L1RCLK, L1TCLK width low (DSC =1)	P + 10	—	ns
83a	L1RCLK, L1TCLK width high (DSC = 1)[3]	P + 10	—	ns
84	L1CLK edge to L1CLKO valid (DSC = 1)	—	30.00	ns
85	$\overline{\text{L1RQ}}$ valid before falling edge of L1TSYNC[4]	1.00	—	L1TCLK
86	L1GR setup time[2]	42.00	—	ns
87	L1GR hold time	42.00	—	ns
88	L1CLK edge to L1SYNC valid (FSD = 00) CNT = 0000, BYT = 0, DSC = 0)	—	0.00	ns

1 The ratio SyncCLK/L1RCLK must be greater than 2.5/1.

2 These specs are valid for IDL mode only.

3 Where P = 1/CLKOUT. Thus, for a 25-MHz CLKO1 rate, P = 40 ns.

4 These strobes and TxD on the first bit of the frame become valid after L1CLK edge or L1SYNC, whichever is later.

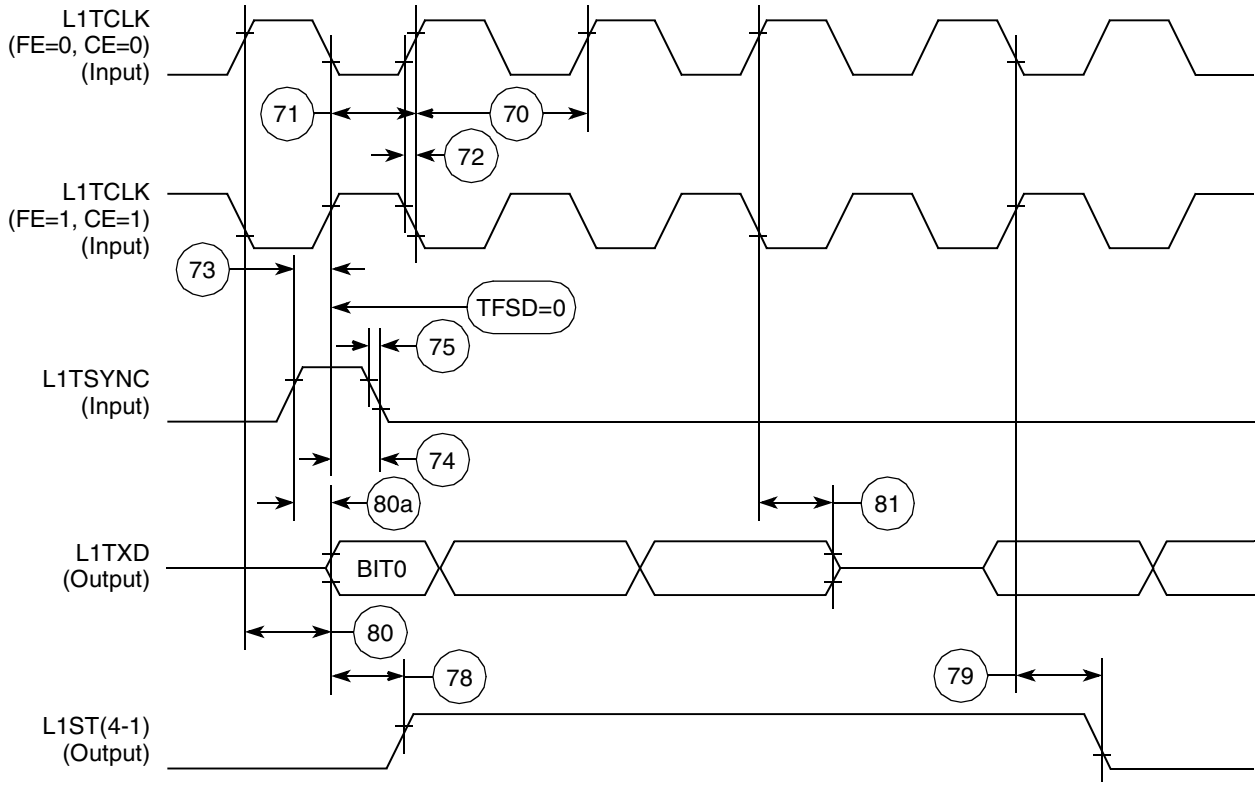
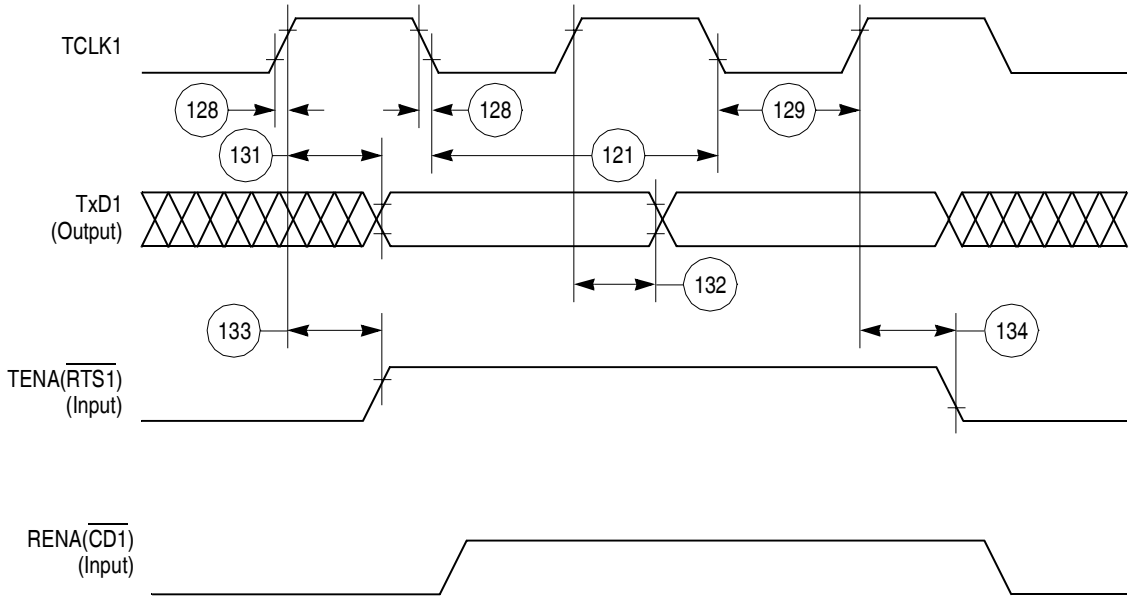


Figure 55. SI Transmit Timing Diagram (DSC = 0)



Notes:
1. Transmit clock invert (TCI) bit in GSMR is set.
2. If RENA is deasserted before TENA, or RENA is not asserted at all during transmit, then the CSL bit is set in the buffer descriptor at the end of the frame transmission.

Figure 63. Ethernet Transmit Timing Diagram

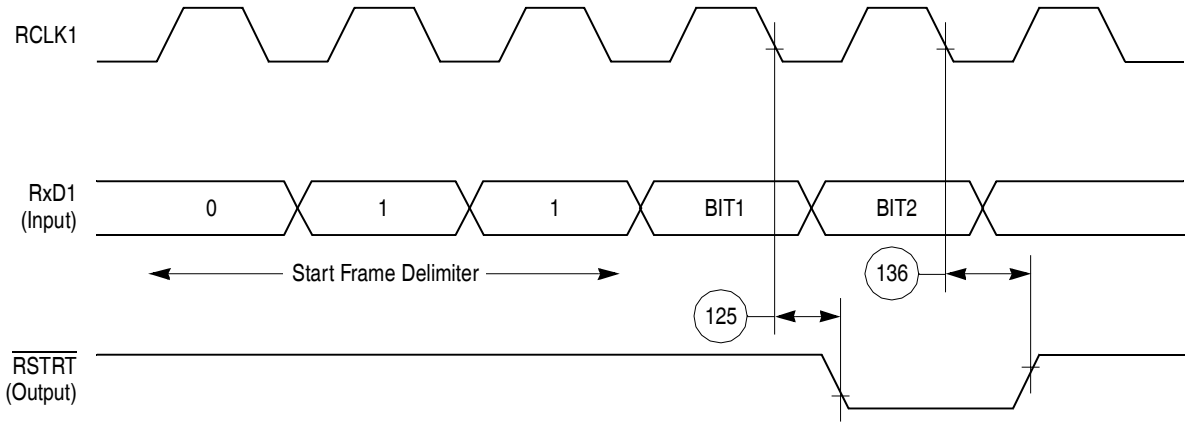


Figure 64. CAM Interface Receive Start Timing Diagram

Figure 65. CAM Interface REJECT Timing Diagram

12.9 SMC Transparent AC Electrical Specifications

Table 25 shows the SMC transparent timings as shown in Figure 66.

Table 39. Pin Assignments (continued)

Name	Pin Number	Type
$\overline{BR}$	G4	Bidirectional
$\overline{BG}$	E2	Bidirectional
$\overline{BB}$	E1	Bidirectional Active Pull-up
FRZ $\overline{IRQ6}$	G3	Bidirectional
$\overline{IRQ0}$	V14	Input
$\overline{IRQ1}$	U14	Input
M_TX_CLK $\overline{IRQ7}$	W15	Input
$\overline{CS}$[0:5]	C3, A2, D4, E4, A4, B4	Output
$\overline{CS6}$ $\overline{CE1\_B}$	D5	Output
$\overline{CS7}$ $\overline{CE2\_B}$	C4	Output
$\overline{WE0}$ $\overline{BS\_B0}$ $\overline{IORD}$	C7	Output
$\overline{WE1}$ $\overline{BS\_B1}$ $\overline{IOWR}$	A6	Output
$\overline{WE2}$ $\overline{BS\_B2}$ $\overline{PCOE}$	B6	Output
$\overline{WE3}$ $\overline{BS\_B3}$ $\overline{PCWE}$	A5	Output
$\overline{BS\_A}$[0:3]	D8, C8, A7, B8	Output
$\overline{GPL\_A0}$ $\overline{GPL\_B0}$	D7	Output
$\overline{OE}$ $\overline{GPL\_A1}$ $\overline{GPL\_B1}$	C6	Output
$\overline{GPL\_A}$[2:3] $\overline{GPL\_B}$[2:3] $\overline{CS}$[2–3]	B5, C5	Output
UPWAITA $\overline{GPL\_A4}$	C1	Bidirectional

Table 39. Pin Assignments (continued)

Name	Pin Number	Type
PA5 CLK3 L1TCLKA BRGO2 TIN2	N18	Bidirectional
PA4 CLK4 $\overline{\text{TOUT2}}$	P19	Bidirectional
PA3 CLK5 BRGO3 TIN3	P17	Bidirectional
PA2 CLK6 $\overline{\text{TOUT3}}$ L1RCLKB	R18	Bidirectional
PA1 CLK7 BRGO4 TIN4	T19	Bidirectional
PA0 CLK8 $\overline{\text{TOUT4}}$ L1TCLKB	U19	Bidirectional
PB31 $\overline{\text{SPISEL}}$ $\overline{\text{REJECT1}}$	C17	Bidirectional (Optional: Open-drain)
PB30 SPICLK $\overline{\text{RSTRT2}}$	C19	Bidirectional (Optional: Open-drain)
PB29 SPIMOSI	E16	Bidirectional (Optional: Open-drain)
PB28 SPIMISO BRGO4	D19	Bidirectional (Optional: Open-drain)
PB27 I2CSDA BRGO1	E19	Bidirectional (Optional: Open-drain)
PB26 I2CSCL BRGO2	F19	Bidirectional (Optional: Open-drain)

Table 39. Pin Assignments (continued)

Name	Pin Number	Type
PB16 $\overline{\text{L1RQa}}$ L1ST4 $\overline{\text{RTS4}}$ PHREQ0[1] RXADDR0[2]	N16	Bidirectional (Optional: Open-drain)
PB15 BRGO3 TxClav RxClav	R17	Bidirectional
PB14 RXADDR2[2] $\overline{\text{RSTRT1}}$	U18	Bidirectional
PC15 $\overline{\text{DREQ0}}$ $\overline{\text{RTS1}}$ L1ST1 RxClav TxClav	D16	Bidirectional
PC14 $\overline{\text{DREQ1}}$ $\overline{\text{RTS2}}$ L1ST2	D18	Bidirectional
PC13 $\overline{\text{L1RQb}}$ L1ST3 RTS3	E18	Bidirectional
PC12 $\overline{\text{L1RQa}}$ L1ST4 RTS4	F18	Bidirectional
PC11 $\overline{\text{CTS1}}$	J19	Bidirectional
PC10 $\overline{\text{CD1}}$ $\overline{\text{TGATE1}}$	K19	Bidirectional
PC9 $\overline{\text{CTS2}}$	L18	Bidirectional
PC8 $\overline{\text{CD2}}$ $\overline{\text{TGATE2}}$	M18	Bidirectional

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